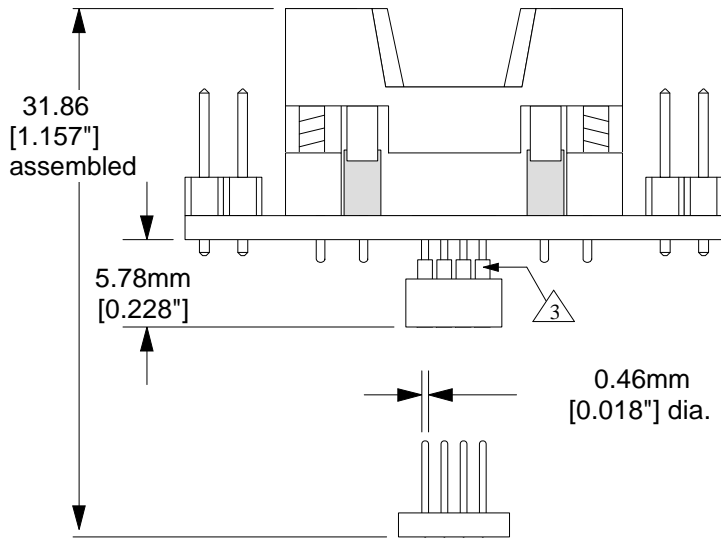
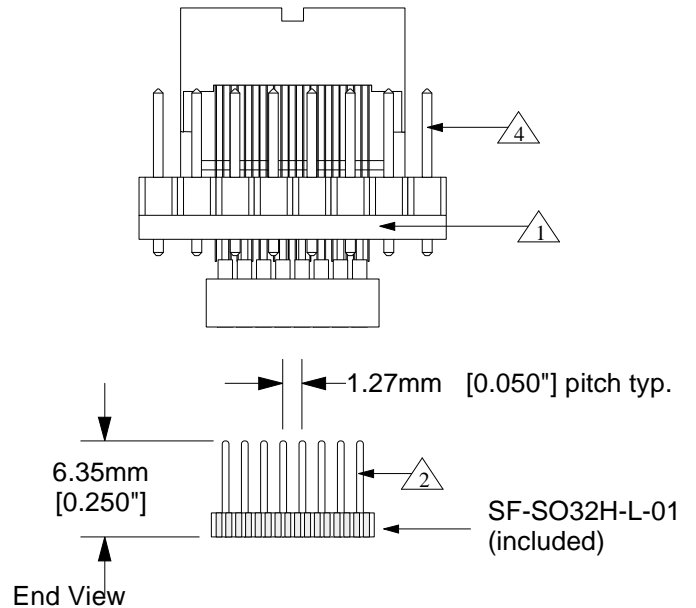


Top View

- 1 Substrate: 1.59mm \pm 0.18mm [0.0625" \pm 0.007"] FR4/G10 or equivalent high temp material. 17 μ m [1/2 oz.] Cu clad. SnPb plating.
- 2 Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25 μ m [10 μ "] Au over 1.27 μ m [50 μ "] Ni (min.).
- 3 Pins: shell material- Brass Alloy 360 1/2 hard; finish- 0.25 μ m [10 μ "] Au over 1.27 μ m [50 μ "] Ni (min.). Contact material- BeCu; finish 0.25 μ m [10 μ "] Au over 2.54 μ m [100 μ "] Ni (min.).
- 4 Test points: material- Phosphor Bronze; plating- Sn over 1.27 μ m [50 μ "] Ni. Gold flash on contact end.



Side View




End View

Description: SOIC Carrier Adaptor

32 position 0.65 mm pitch open top TSSOP ZIF socket to 32 position 0.65 mm pitch SOIC emulator foot.

Tolerances: diameters \pm 0.03mm [\pm 0.001"], PCB perimeters \pm 0.13mm [\pm 0.005"], PCB thicknesses \pm 0.18mm [\pm 0.007"], pitches (from true position) \pm 0.08mm [\pm 0.003"], all other tolerances \pm 0.13mm [\pm 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

CA-SO32H-L-Z-T-01 Drawing		Status: Released	Scale: 2:1	Rev: A
	© 2000 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com		Drawing: E Smolentseva	
			Date: 03/13/00	
			File: CA-SO32H-L-Z-T-01 Dwg.mcd	Modified: